

- Delay Elements for Generating Delay Lines
- Inverting and Non-inverting Elements
- Buffer NAND Elements Rated at I_{OL} of 12/24 mA
- PNP Inputs Reduce Fan-In ($I_{IL} = -0.2$ mA MAX)
- Worst Case MIN/MAX Delays Guaranteed Across Temperature and V_{CC} Ranges

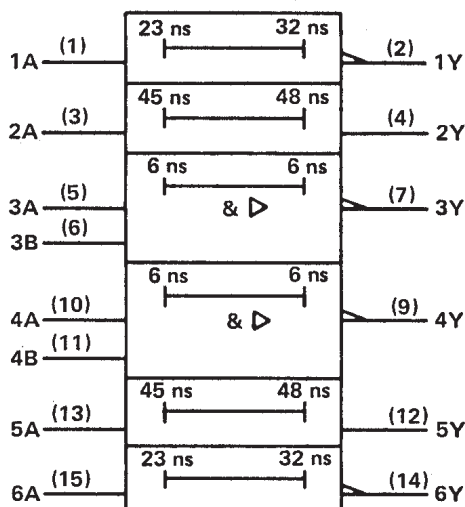
description

These 'LS31 delay elements are intended to provide well-defined delays across both temperature and V_{CC} ranges. Used in cascade, a limitless range of delay gating is possible.

All inputs are PNP with I_{IL} MAX of -0.2 mA. Gates 1, 2, 5, and 6 have standard Low-Power Schottky output sink current capability of 4 and 8 mA I_{OL} . Buffers 3 and 4 are rated at 12 and 24 mA.

The SN54LS31 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74LS31 is characterized for operation from 0°C to 70°C .

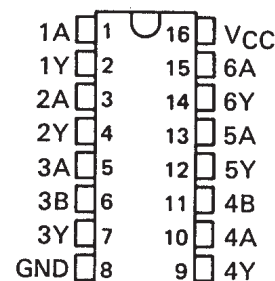
logic symbol†



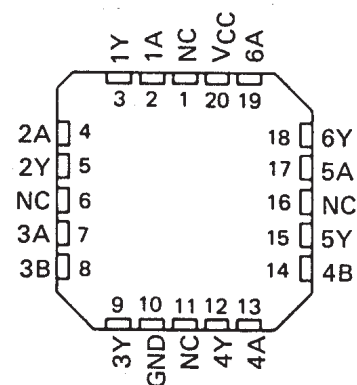
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54LS31 . . . J OR W PACKAGE
SN74LS31 . . . D OR N PACKAGE
(TOP VIEW)



SN54LS31 . . . FK PACKAGE
(TOP VIEW)

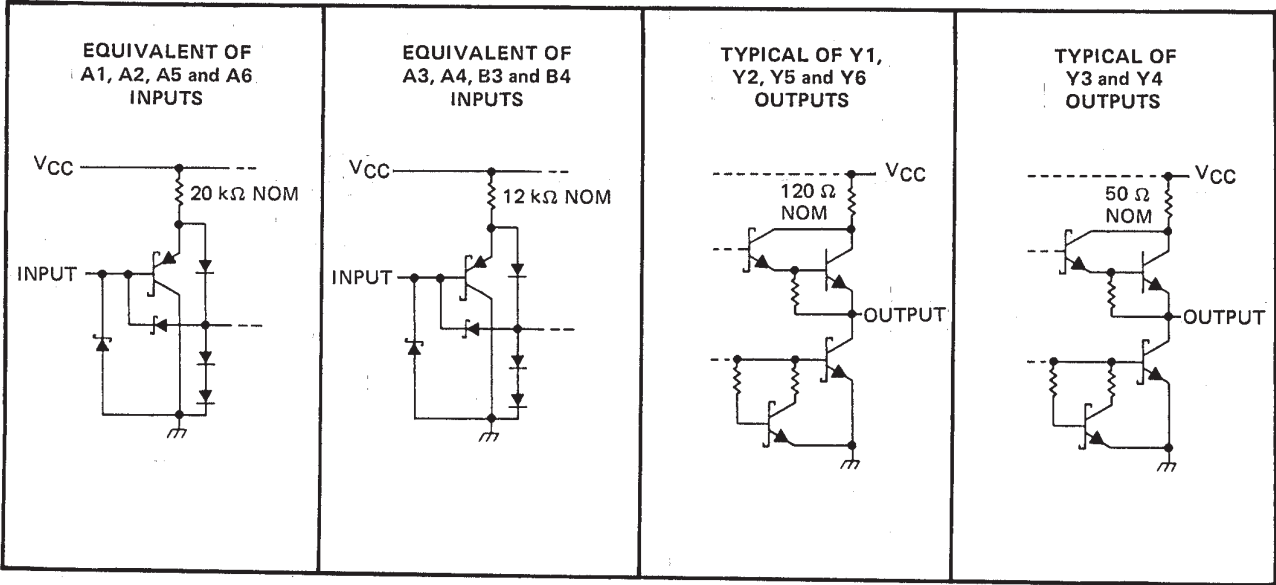


NC - No internal connection

SN54LS31, SN74LS31
DELAY ELEMENTS

SDLS157 – DECEMBER 1983 – REVISED MARCH 1988

| Delay Element | Logic | Typical Delays | | | Rated I _{OL} |
|-----------------|---------------|------------------|------------------|---------|-----------------------|
| | | t _{PLH} | t _{PHL} | AVG. | |
| Gates 1 and 6 | Inverting | 32 ns | 23 ns | 27.5 ns | 4 and 8 mA |
| Gates 2 and 5 | Non-Inverting | 45 ns | 48 ns | 46.5 ns | 4 and 8 mA |
| Buffers 3 and 4 | 2-Input NAND | 6 ns | 6 ns | 6 ns | 12 and 24 mA |



absolute maximum ratings over operating free air temperature range (unless otherwise noted)

| | |
|--|-------------------|
| Supply voltage, V _{CC} (See Note 1) | 7 V |
| Input voltage, V _I : All inputs | 7 V |
| Operating free-air temperature range: SN54LS31 | – 55° C to 125° C |
| SN74LS31 | 0° C to 70° C |
| Storage temperature range | – 65° C to 150° C |

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

| | | SN54LS31 | | | SN74LS31 | | | UNIT |
|-----------------|--------------------------------|----------|-----|-------|----------|-----|-------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| V _{CC} | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| V _{IH} | High-level input voltage | 2 | | | 2 | | | V |
| V _{IL} | Low-level input voltage | | | 0.7 | | | 0.8 | V |
| I _{OH} | High-level output current | | | – 1.2 | | | – 1.2 | mA |
| | | | | – 0.4 | | | – 0.4 | |
| I _{OL} | Low-level output current | | | 12 | | | 24 | mA |
| | | | | 4 | | | 8 | |
| T _A | Operating free-air temperature | – 55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS† | | | | SN54LS31 | | | SN74LS31 | | | UNIT |
|-------------------|------------------|---|--|----------------------------|----------------|----------|-------|----------|----------|------|-----|------|
| | | | | | | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | |
| V _{IK} | | V _{CC} = MIN, I _I = − 18 mA | | | | − 1.5 | | | − 1.5 | | | V |
| V _{OH} | | V _{CC} = MIN, V _{IL} = MAX | V _{IH} = 2 V, Y3, Y4 Others | I _{OH} = − 1.2 mA | 2.4 | 3.1 | | 2.4 | 3.1 | | V | |
| | | | | I _{OH} = − 0.4 mA | 2.5 | 3.1 | | 2.7 | 3.1 | | | |
| V _{OL} | | V _{CC} = MIN, V _{IL} = MAX | Y3, Y4 | I _{OL} = 12 mA | 0.25 0.4 | | | 0.25 0.4 | | | V | |
| | | | | I _{OL} = 24 mA | | | | 0.35 0.5 | | | | |
| | | | Others | I _{OL} = 4 mA | 0.25 0.4 | | | 0.25 0.4 | | | | |
| | | | | I _{OL} = 8 mA | | | | 0.35 0.5 | | | | |
| I _I | | V _{CC} = MAX, V _I = 7 V | | | | 0.1 | | | 0.1 | | | mA |
| I _{IH} | | V _{CC} = MAX, V _I = 2.7 V | | | | 20 | | | 20 | | | μA |
| I _{IL} | | V _{CC} = MAX, V _I = 0.4 V | | | | − 0.2 | | | − 0.2 | | | mA |
| I _{OS} § | | V _{CC} = MAX, A3, A4, B3, B4 = 0 V | | | Y3, Y4 | − 30 | − 130 | − 30 | − 130 | mA | | |
| | | V _{CC} = MAX, A1, A6 = 0 V, A2, A5 = 4.5 V | | | Y1, Y2, Y5, Y6 | − 20 | − 100 | − 20 | − 100 | | | |
| I _{CC} | I _{CCH} | V _{CC} = MAX, A2, A5 = 4.5 V, all other inputs 0 V | | | | 2.3 | 4 | 2.3 | 4 | mA | | |
| | I _{CCL} | V _{CC} = MAX, A2, A5 = 0 V, all other inputs 4.5 V | | | | 13 | 20 | 13 | 20 | | | |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics, (see note 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN54LS31 | | | SN74LS31 | | | UNIT |
|-----------|-------------------|----------------|----------|-----|-----|----------|-----|-----|------|
| | | | MIN | TYP | MAX | MIN | TYP | MAX | |
| t_{PLH} | A1, A6 | Y1, Y6 | 15 | | 70 | 22 | | 65 | ns |
| t_{PHL} | | | 9 | | 50 | 13 | | 45 | |
| t_{PLH} | A2, A5 | Y2, Y5 | 22 | | 90 | 31 | | 80 | ns |
| t_{PHL} | | | 20 | | 105 | 30 | | 95 | |
| t_{PLH} | A3, B3, A4, Y4 | Y3, Y4 | 2 | | 20 | 2 | | 15 | ns |
| t_{PHL} | | | 2 | | 20 | 2 | | 15 | |

NOTE 2: $V_{CC} = \text{MIN to MAX}$

$R_L = 667 \Omega, C_L = 45 \text{ pF}$ for Y3 and Y4.

$R_L = 2 \text{ k}\Omega, C_L = 15 \text{ pF}$ for Y1, Y2, Y5 and Y6.

$T_A = \text{MIN to MAX}$

Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

| Orderable part number | Status (1) | Material type (2) | Package Pins | Package qty Carrier | RoHS (3) | Lead finish/ Ball material (4) | MSL rating/ Peak reflow (5) | Op temp (°C) | Part marking (6) |
|-----------------------------|---------------|----------------------|----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| SN74LS31D | Active | Production | SOIC (D) 16 | 40 TUBE | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS31 |
| SN74LS31D.A | Active | Production | SOIC (D) 16 | 40 TUBE | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | LS31 |
| SN74LS31N | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | 0 to 70 | SN74LS31N |
| SN74LS31N.A | Active | Production | PDIP (N) 16 | 25 TUBE | Yes | NIPDAU | N/A for Pkg Type | 0 to 70 | SN74LS31N |
| SN74LS31NSR | Active | Production | SOP (NS) 16 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74LS31 |
| SN74LS31NSR.A | Active | Production | SOP (NS) 16 | 2000 LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74LS31 |

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LS31NSR | SOP | NS | 16 | 2000 | 330.0 | 16.4 | 8.1 | 10.4 | 2.5 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LS31NSR | SOP | NS | 16 | 2000 | 353.0 | 353.0 | 32.0 |

TUBE



*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|-------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| SN74LS31D | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| SN74LS31D.A | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| SN74LS31N | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74LS31N | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74LS31N.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74LS31N.A | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |



PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



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NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



| PINS ** DIM | 14 | 16 | 18 | 20 |
|---------------------|------------------|------------------|------------------|------------------|
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| MS-001 VARIATION | AA | BB | AC | AD |



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

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